

Description

The NTD4302 uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.

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TO-252-2L

General Features

V_{DS} = 30V I_D =50 A

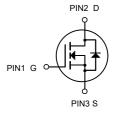
 $R_{DS(ON)}$ < 10m Ω @ V_{GS} =10V

Application

Battery protection

Load switch

Uninterruptible power supply



N-Channel MOSFET

Package Marking and Ordering Information

Product ID	Pack	Brand	Qty(PCS)
NTD4302	TO-252-2L	HXY MOSFET	2500

Absolute Maximum Ratings (T_C=25 ℃ unless otherwise noted)

Symbol	Parameter	Rating	Units	
V _D s	Drain-Source Voltage	30	V	
V _G s	Gate-Source Voltage	±20	V	
I _D @T _C =25°C	Continuous Drain Current, V _{GS} @ 10V ¹	50	А	
I _D @T _C =100°C	Continuous Drain Current, V _{GS} @ 10V ¹	30	А	
Ідм	Pulsed Drain Current ²	112	А	
EAS	Single Pulse Avalanche Energy ³	24.2	mJ	
las	Avalanche Current	22	А	
P _D @T _C =25°C	Total Power Dissipation ⁴	37.5	W	
Тѕтс	Storage Temperature Range	-55 to 175	°C	
TJ	Operating Junction Temperature Range	-55 to 175	°C	
Reja	Thermal Resistance Junction-Ambient ¹	62	°C/W	
R _θ Jc	Thermal Resistance Junction-Case ¹	4 °C/W		

Electrical Characteristics (T_J=25°C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit	
BVDSS	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =250uA	30			V	
∆BVpss/∆Tj	BVDSS Temperature Coefficient	Reference to 25°C , I _D =1mA		0.0193		V/°C	
_	Static Drain-Source On-Resistance ²	V _{GS} =10V , I _D =30A		7.5	10		
RDS(ON)		V _{GS} =4.5V , I _D =15A		11	18	$\boldsymbol{m}\Omega$	
V _G S(th)	Gate Threshold Voltage		1.2		2.5	V	
$\triangle V_{GS(th)}$	V _{GS(th)} Temperature Coefficient	V _{GS} =V _{DS} , I _D =250uA		-3.97		mV/°C	
	Drain-Source Leakage Current	V _{DS} =24V , V _{GS} =0V , T _J =25°C			1	uA	
loss		V _{DS} =24V , V _{GS} =0V , T _J =55°C			5		
Igss	Gate-Source Leakage Current	V _{GS} =±20V , V _{DS} =0V			±100	nA	
gfs	Forward Transconductance	V _{DS} =5V , I _D =30A		34		S	
Rg	Gate Resistance	V _{DS} =0V , V _{GS} =0V , f=1MHz		1.8		Ω	
Qg	Total Gate Charge (4.5V)			9.8			
Qgs	Gate-Source Charge	V _{DS} =15V , V _{GS} =4.5V , I _D =15A		4.2		nC	
Q _{gd}	Gate-Drain Charge			3.6			
T _d (on)	Turn-On Delay Time			4			
Tr	Rise Time	V _{DD} =15V , V _{GS} =10V ,		8			
T _d (off)	Turn-Off Delay Time	R _G =3.3		31		ns	
T _f	Fall Time	I _D =15A		4			
Ciss	Input Capacitance			940			
Coss	Output Capacitance	V _{DS} =15V , V _{GS} =0V , f=1MHz		131		pF	
Crss	Reverse Transfer Capacitance			109			
Is	Continuous Source Current ^{1,5}				43	Α	
Ism	Pulsed Source Current ^{2,5}	V _G =V _D =0V , Force Current			112	Α	
VsD	Diode Forward Voltage ²	V _{GS} =0V , I _S =1A , T _J =25°C			1	V	
t _{rr}	Reverse Recovery Time	IF=30A , dI/dt=100A/µs ,		8.5		nS	
Qrr	Reverse Recovery Charge	IF=30A , dl/dt=100A/μs , T _J =25°C		2.2		nC	

Note:

- 1 .The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width $\leqq 300 us$, duty cycle $\leqq 2\%$
- 3 .The EAS data shows Max. rating . The test condition is V_{DD} =25V, V_{GS} =10V,L=0.1mH, I_{AS} =22A
- 4. The power dissipation is limited by 175°C junction temperature
- 5. The data is theoretically the same as I_D and I_{DM} , in real applications, should be limited by total power dissipation.

Typical Characteristics

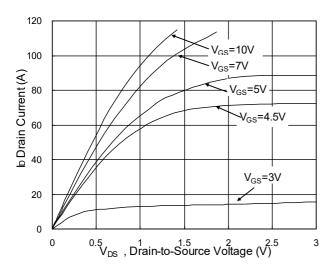


Fig.1 Typical Output Characteristics

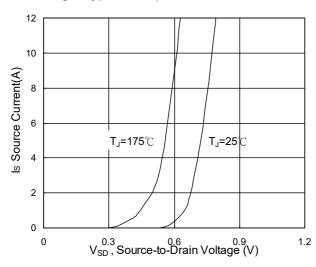


Fig.3 Forward Characteristics of Reverse

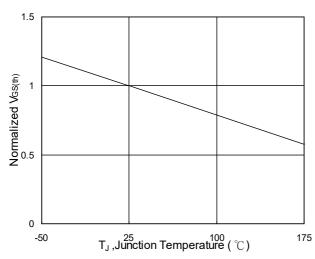


Fig.5 Normalized $V_{\text{GS(th)}}$ vs. T_{J}

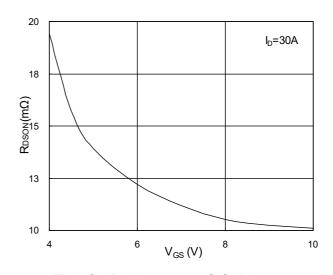


Fig.2 On-Resistance vs. G-S Voltage

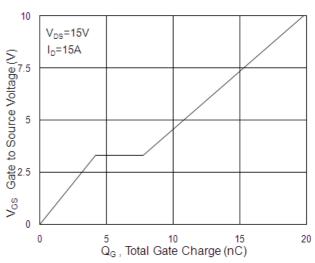


Fig.4 Gate-Charge Characteristics

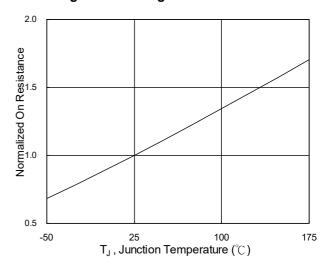
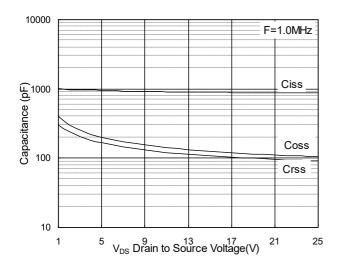


Fig.6 Normalized R_{DSON} vs. T_J



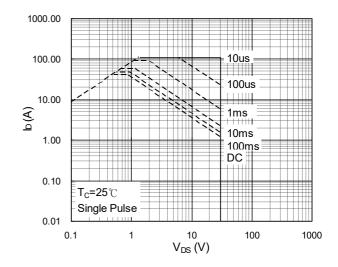


Fig.7 Capacitance

Fig.8 Safe Operating Area

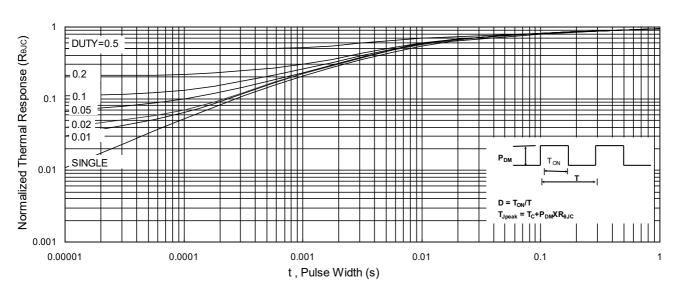


Fig.9 Normalized Maximum Transient Thermal Impedance

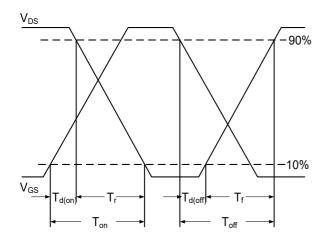


Fig.10 Switching Time Waveform

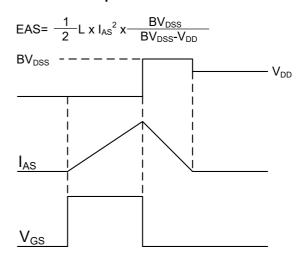
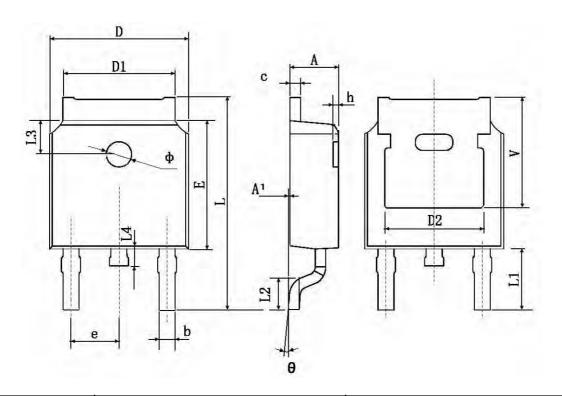


Fig.11 Unclamped Inductive Switching Waveform

TO-252-2L Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches		
	Min.	Max.	Min.	Max.	
А	2.200	2.400	0.087	0.094	
A1	0.000	0.127	0.000	0.005	
b	0.660	0.860	0.026	0.034	
С	0.460	0.580	0.018	0.023	
D	6.500	6.700	0.256	0.264	
D1	5.100	5.460	0.201	0.215	
D2	0.483 TYP.		0.190 TYP.		
Е	6.000	6.200	0.236	0.244	
е	2.186	2.386	0.086	0.094	
L	9.800	10.400	0.386	0.409	
L1	2.900 TYP.		0.114 TYP.		
L2	1.400	1.700	0.055	0.067	
L3	1.600 TYP.		0.063 TYP.		
L4	0.600	1.000	0.024	0.039	
Ф	1.100	1.300	0.043	0.051	
θ	0°	8°	0°	8°	
h	0.000	0.300	0.000	0.012	
V	5.350	5.350 TYP. 0.211 TYP.		TYP.	



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